

ADVANCING WHAT'S NEXT



2026 Investor Day

New York City | May 21

Welcome & Opening Remarks



Jennifer Jue | VP, Investor Relations

Safe Harbor Statements

Non-GAAP Measures

This presentation contains certain measures that are not defined terms under U.S. generally accepted accounting principles ("GAAP"). These non-GAAP measures should not be considered in isolation or as a substitute for, or superior to, measures of liquidity or performance prepared in accordance with U.S. GAAP and may not be comparable to calculations of similarly titled measures by other companies. See the Appendix for a description of these financial measures and a reconciliation of all such non-GAAP financial measures to the most directly comparable U.S. GAAP financial measures.

Forward-Looking Statement Disclaimer

This presentation contains forward-looking statements within the meaning of the federal securities laws. You are cautioned not to place undue reliance on forward-looking statements, which are often characterized by terminology such as "may," "will," "should," "expects," "plans," "anticipates," "believes," "estimates," "predicts," "potential," "continue," or "intend," by the negative of these terms or other comparable terminology or by discussions of strategy, plans or intentions. All forward-looking statements in this presentation are made based on our current expectations, forecasts, estimates and assumptions. Because such statements include risks and uncertainties, actual results may differ materially from those anticipated in such forward-looking statements as a result of various factors, including those set forth in our Annual Report on Form 10-K for the year ended December 31, 2025 (the "Form 10-K") and from time to time in our other reports filed with or furnished to the Securities and Exchange Commission ("SEC"). You should carefully consider the trends, risks and uncertainties described in this presentation, the Form 10-K and other reports filed with or furnished to the SEC before making any investment decision with respect to our securities. If any of these trends, risks or uncertainties continues or occurs, our business, financial condition or operating results could be materially and adversely affected, the trading prices of our securities could decline, and you could lose part or all of your investment. All forward-looking statements attributable to us or persons acting on our behalf are expressly qualified in their entirety by this cautionary statement. We assume no obligation to review or update any forward-looking statements to reflect events or circumstances occurring after the date of this presentation, except as may be required by applicable law.



2026 Investor Day Agenda

9:00 AM **Welcome and Opening Remarks**

Jennifer Jue | VP, Investor Relations

Leading the Next Era of Advanced Packaging

Kevin Engel | President & Chief Executive Officer

Enhancing Strategic Partnerships in Key Markets

Farshad Haghighi | EVP, Chief Sales Officer

Elevating Technology Leadership with Advanced Packaging

Doug Scott | CVP, Advanced & Mainstream Business Units

10:15 AM **Break**

10:30 AM **Expanding Geographic Footprint**

Doug Scott | CVP, Advanced & Mainstream Business Units

Turning Strategy Into Earnings Power

Megan Faust | EVP, Chief Financial Officer

11:10 AM **Q&A Session with All Presenters**

Invest with Us

Kevin Engel | President & Chief Executive Officer

12:00 PM **Leadership Luncheon**

Leading the Next Era of Advanced Packaging

Differentiated Technology, Strategic Partnerships,
and Scalable Global Execution



Kevin Engel | President & Chief Executive Officer

An Advanced Packaging-Led Era is Here

1 Structural shift

Structural changes are reshaping the industry, and Advanced packaging is on the critical path

2 Amkor's growth engine

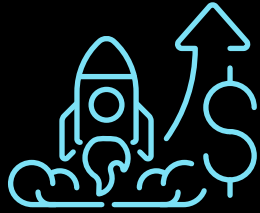
Advanced packaging is Amkor's growth engine, and we are scaling our partnerships, technology, and footprint to deliver at scale

3 Multi-year value creation

Amkor is on a multi-year value creation path, investing today to drive a materially stronger earnings model over time



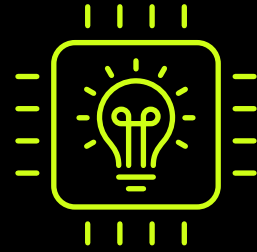
Forces Driving a Structural Shift



Accelerated Market Growth

Beyond \$1 trillion

AI proliferation drives
expansion of HPC



Technology Transition

Moore's Law slowing

Advanced packaging
drives innovation



Evolving Supply Chains

Global to regional

Driven by geopolitics,
trade, national security

Strategically Positioned to Capture Tailwinds from a New Era of Advanced Packaging

What an Advanced Packaging-Led Era Requires

Scalable, manufacturable Advanced packaging platforms

Earlier engagement and deeper customer alignment

Regional delivery capability

Amkor is Intentionally Aligned to this Shift

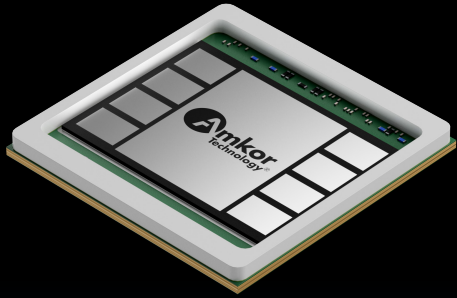
Partnerships evolving with earlier design engagement and supply security

Technology platforms designed for repeatable execution at scale

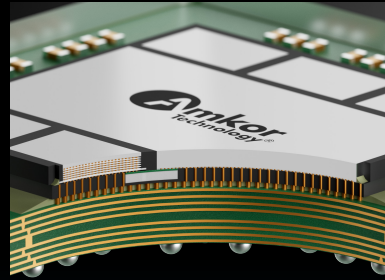
Purpose-built footprint to support regional delivery

Advanced Packaging Content Per End System is Structurally Increasing

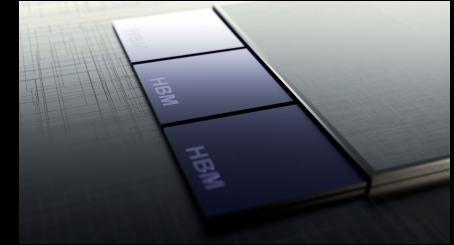
DRIVING FORCES BEHIND THE INCREASE



Chiplet-based Architectures



Complexity and Content Growth



Packaging Scaling

RISING ECONOMIC IMPACT: 2025-2030E

>20% CAGR

Server market and gigawatt install

~\$0.5B TAM

Per gigawatt install

~3x TAM

in OSAT server Advanced packaging

Sources: McKinsey, Gartner, management estimates

Strategy to Deliver Shareholder Value

Enhance Strategic Partnerships in Key Markets

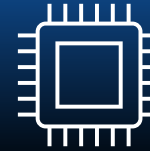


Partnerships evolving with earlier design engagement

Planning horizons are becoming multi-year

Commitments improve visibility and predictability

Elevate Technology Leadership



Early co-development drives earlier, deeper customer engagement

Scalable 2.5D and HDFO platforms support repeatable adoption

Turnkey execution, including test, enables quality, reliability, and speed

Expand Geographic Footprint



An intentionally built footprint to support regional delivery

Arizona facility increases diversification of Advanced packaging footprint

Supply security is a requirement

Long-Term Financial Targets

	2025 Results ⁽¹⁾	2028 Targets	2030 Targets
Revenue	\$6.7B	\$9.0B +/- \$500M	~\$11B+
Gross Margin	14%	17.5% +/- 100bps	~22%+
EPS	\$1.50	\$2.50 +/- \$0.25	~\$5.00+

KEY ASSUMPTIONS

Mix shift towards higher-value packaging drives margin and earnings expansion

Initial ramp up costs in 2027 and 2028 with AZ buildout

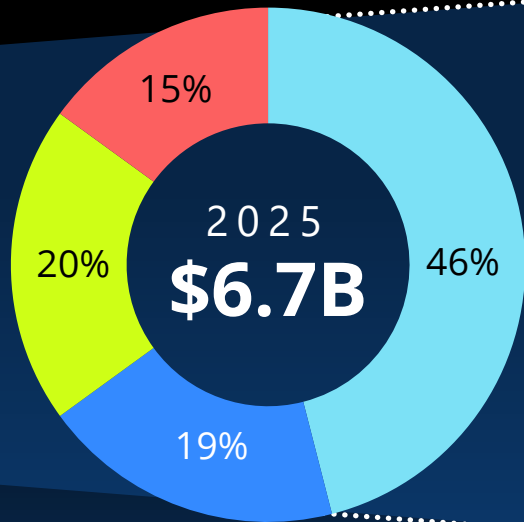
Revenue growth accelerates in 2029–2030 as AZ facility scales

20% planning effective tax rate

See corresponding endnotes on slide 71.

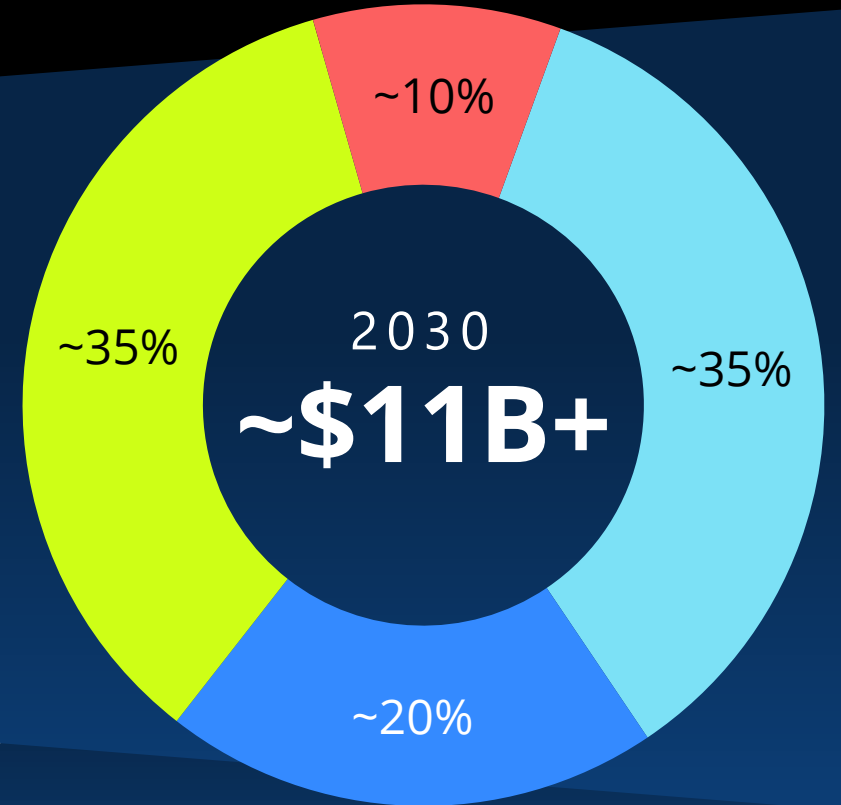
Amkor End Market Model

ESTIMATED MIX SHIFT WITH OUTSIZED HPC/AI GROWTH



Estimated End Market CAGRs (2025-2030)

- ~24%** Computing
- ~10%** Automotive & Industrial
- ~4%** Communications
- ~3%** Consumer



An Experienced Team Aligned to Execute & Deliver

Seasoned operators focused on shareholder value creation



Kevin Engel

President,
Chief Executive Officer
30+ Years



Megan Faust

EVP,
Chief Financial Officer
30+ Years



Farshad Haghghi

EVP,
Chief Sales Officer
40+ Years



Doug Scott

CVP, Advanced and
Mainstream Business Units
25+ Years

Today's Speakers



Mark Rogers

EVP, General Counsel, and
Corporate Secretary
30+ Years



John Liu

EVP, Corporate
Development and Strategy
30+ Years



Detlef Nagel

CVP,
Global Operations
25+ Years



KyungRok Park

CVP,
Head of Global R&D
25+ Years



Bob Lanzone

CVP, System in Package
Business Unit
35+ Years

Leading the Next Era Key Takeaways

1

Structural changes are reshaping the industry, and Advanced packaging is on the critical path

2

Advanced packaging is Amkor's growth engine, and we are scaling our partnerships, technology, and footprint

3

Amkor is on a multi-year value creation path, investing today to drive a materially stronger earnings model over time

Enhancing Strategic Partnerships in Key Markets



Farshad Haghghi | EVP, Chief Sales Officer

Partnerships in an Advanced Packaging-Led Era



1 Structural industry shift

Evolving end markets driving deeper, more strategic engagement

2 Co-development and early engagement

Roadmap alignment and planning horizons extend to ensure critical customer needs are met

3 Enhanced engagement enables financial visibility

Reducing risk and improving capital efficiency, utilization, and profitability through the cycle

High Performance Computing

Amkor's Capabilities Support All Big Data Requirements

- ✓ Hyperscale cloud computing
- ✓ Artificial intelligence
- ✓ Training and inference
- ✓ NAND storage
- ✓ Network switches
- ✓ AI accelerators

MEGATREND DRIVERS

GPU, CPU, NPU, AI accelerators

Massive AI workloads

- Compute performance 100 → 10,000 ZFLOPS
- Rack density >100 kW → 1MW
- Token demand growing 600X to >1.2k quintillion

>2x increase in data center server TAM

- Server TAM: ~\$200B → >\$500B

Sources: Gartner, McKinsey, management estimates

2.5D/HDFO Advanced packaging, chiplets architecture and integration
hyperscalers and ASICs providers

Automotive and Industrial

Software Defined Vehicles and Electrification

- ✓ ADAS
- ✓ Infotainment
- ✓ Domain controllers
- ✓ LIDAR / radar sensors
- ✓ In-car networking
- ✓ SiC power modules

MEGATREND DRIVERS

1.5x increase in semiconductor value per vehicle

- Content per vehicle towards \$2,000+
- ADAS content per vehicle towards \$400+

Autonomous and software-defined functionality

- Adds \$250+ incremental semiconductors
- Supports vehicle intelligent and continuous software upgrades

Sources: Gartner, management estimates

Advanced flip chip, MEMS and wirebond packaging
IDM and fabless

Communications

Amkor Supports Nearly All Smartphone Functions

- ✓ Baseband modem
- ✓ AI apps processor
- ✓ Sub-system modules
- ✓ RF front end
- ✓ Storage and sensors
- ✓ Wireless charging



MEGATREND DRIVERS

1.2x avg semiconductor increase per phone

→ Premium tier smartphones higher: \$225 → \$400

On-device AI, 5G, and RF functionality

→ Advanced SoC, increased RF: content >\$20 per smartphone

→ Imaging and sensors increasing 1.1x towards >\$25 per smartphone

Transitioning toward SLM to power edge intelligence

Sources: Gartner, management estimates

Advanced flip chip, SiP, MEMS and memory, wafer level packaging
iOS and Android premium tier

Consumer

Amkor is Enabling the Proliferation of IoT

- ✓ Connectivity / GPS
- ✓ System modules
- ✓ PMIC and sensors
- ✓ Apps processor
- ✓ Wireless charging
- ✓ Security / NFC



MEGATREND DRIVERS

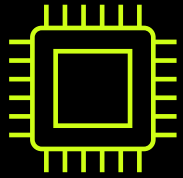
Ultra small form factor with multiple functions

Hearables, wearables, fitness and health, smart homes

Smart edge-AI IoT devices

SiP and wafer level packaging
IDM and fabless

End Markets: Where Technology & Scale Matter Most



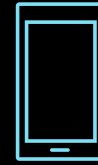
High Performance Computing

HBM integration
Power delivery
Thermal control
Large and complex packages



Automotive & Industrial

Long lifecycles
Zero defect reliability
Supply continuity



Communications

High functional integration
Seasonal cycles
High volume



Consumer Products

High functional integration
Seasonal cycles
High volume

Earlier engagement and structured partnerships improve visibility and durability across end markets

Early Package Co-Development

Device & Package Optimization

Electrical / thermal / stress simulation

Materials selection (e.g., underfill, thermal interface materials)

Quality and reliability engineered early

Manufacturing Readiness

Design-for-manufacturing discipline

Yield learning loops

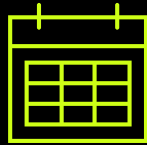
Qualification and ramp planning

Architecture choices increasingly locked early;
we engage before design freezes

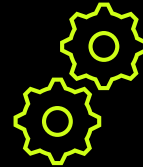
Engagement Evolution Driving Deeper Partnerships



Engagement is moving earlier in the design cycle



Planning horizons are becoming multi-year



Capacity decisions are increasingly pre-aligned



Commitments improve visibility and predictability

FROM
Tactical Accessibility and Cost

Short planning horizons

Capacity access late in cycle

Component-level optimization

Handoffs across suppliers



TO
Strategic Partnerships

Multi-year roadmap alignment

Predictable ramp and delivery

System-level risk reduction

Fewer handoffs, closer collaboration

Innovation Enabled by Trusted Collaboration

“

Amkor is a critical partner in helping us build an end-to-end US silicon supply chain.

For so many years, our partners at Amkor have helped us push the limits of innovation.

They deliver the quality and scale our products demand and we can't wait until they are packaging the Apple silicon produced just down the road at TSMC's new facility.”

—Sabih Khan | COO, Apple

Why Deeper Engagements Improve the Economics

- ✓ Greater visibility enables disciplined capacity planning
- ✓ Planning improves utilization through ramps and cycles
- ✓ Risk is shared earlier in the investment curve
- ✓ Higher utilization supports more resilient returns over time



Deep & Trusted Partner to Global Semiconductor Leaders

80% of Engagements >30 Years



Enhancing Strategic Partnerships Key Takeaways

1

Evolving end markets drive deeper, more strategic engagement

2

Co-development and early engagement drive roadmap alignment to ensure critical customer needs are met

3

Enhanced engagement reduces risk and improves capital efficiency, utilization, and profitability through the cycle

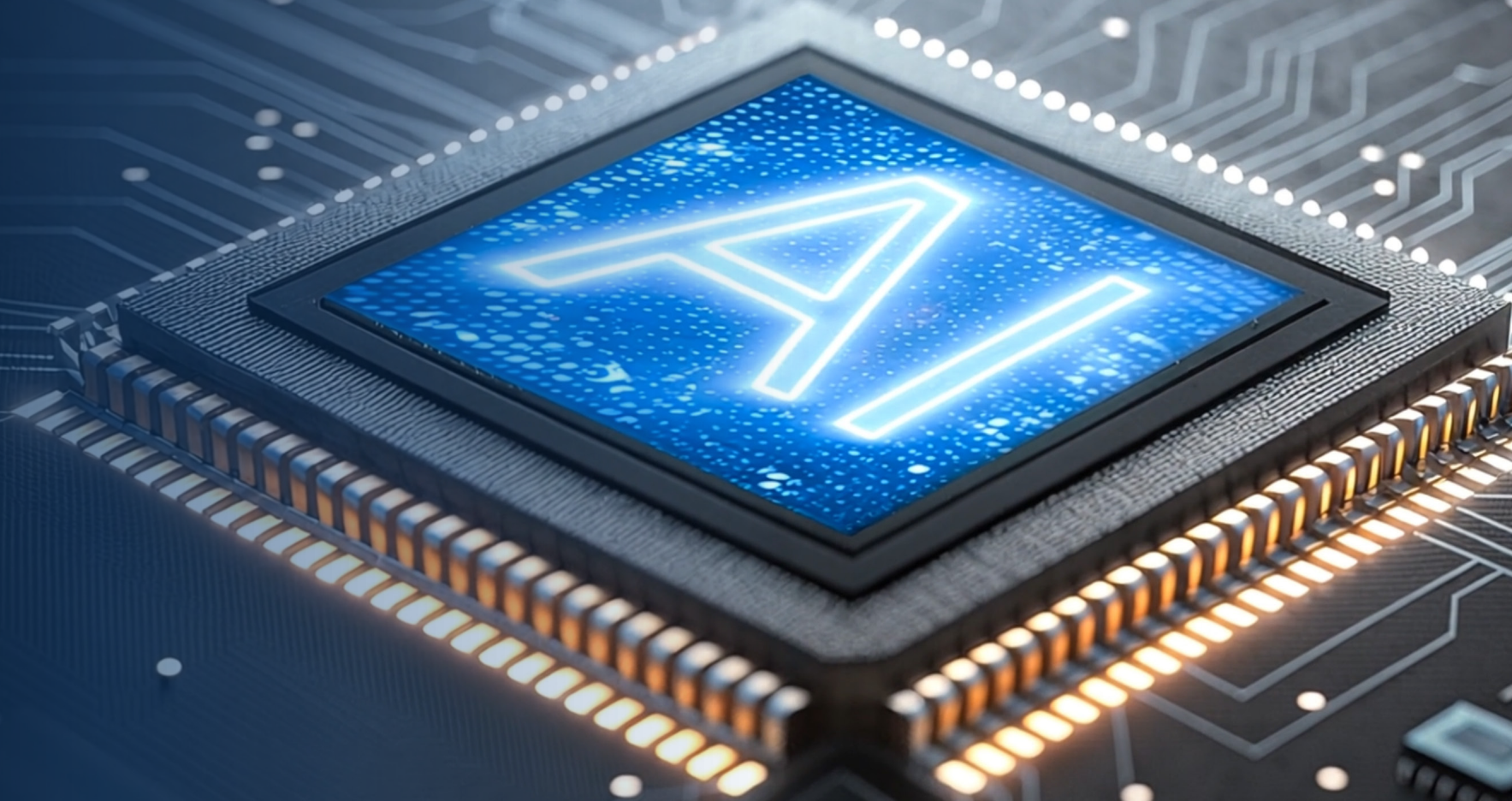
Elevating Technology Leadership

with Advanced Packaging



Doug Scott | CVP, Advanced & Mainstream Business Units

AI Driving Growth of Integrated Products



Technology for an Advanced Packaging-Led Era

1 Co-development is critical to Advanced packaging

Solving complex power, performance, and form factor requirements with Advanced packaging design and materials

2 Our Advanced packaging roadmap is built for scale

Technology roadmap is in lock-step with strategic customers

3 Full turnkey execution

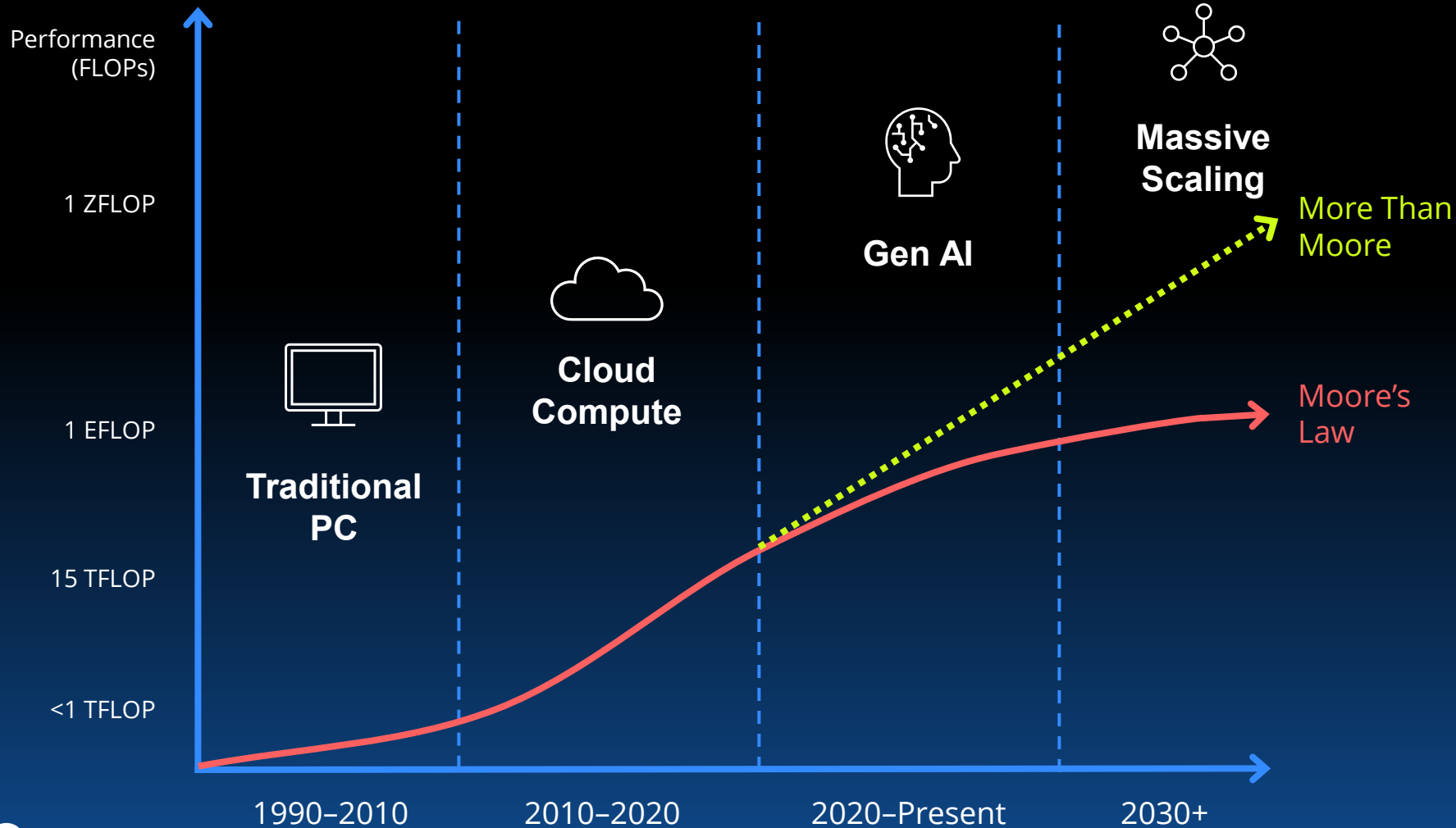
Accelerating Advanced packaging and test investments to reduce cycle time, improve yields, and deliver consistent execution

4 Technology leadership drives earnings power

Higher-value product mix and margin accretion as solutions scale into volume production

From Chips to Systems of Chips

Advanced Packaging Unlocks Performance



“

It may prove to be more economical to build large systems out of smaller functions, which are separately packaged and interconnected.”

– Gordon E. Moore

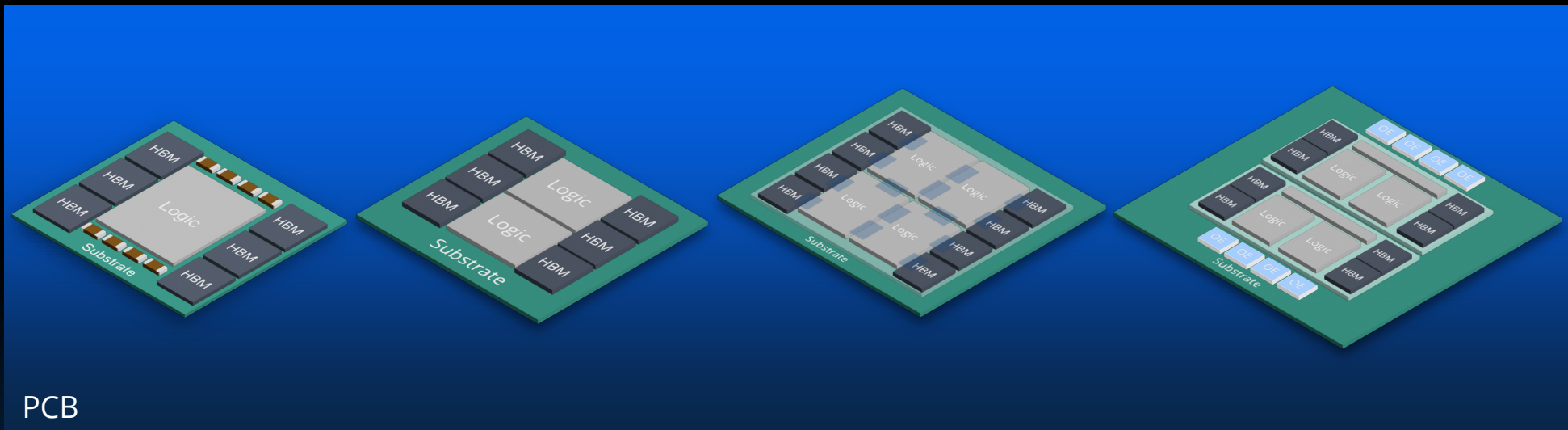
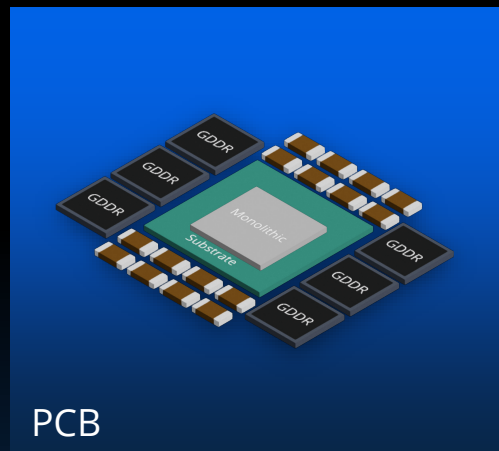
Packaging Complexity Evolution

Monolithic SoC

Optimized single-die performance

Heterogeneous Integration

Modular system-level scaling



PACKAGE SIZE

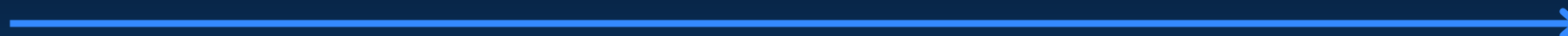
45x45mm²

85x85mm²

>100x100mm²

>150x150mm²

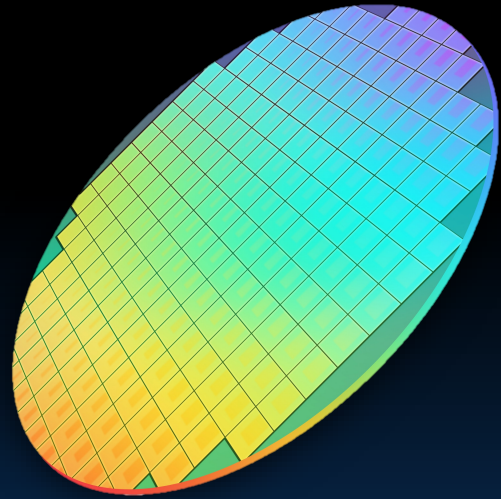
PACKAGE SCALING



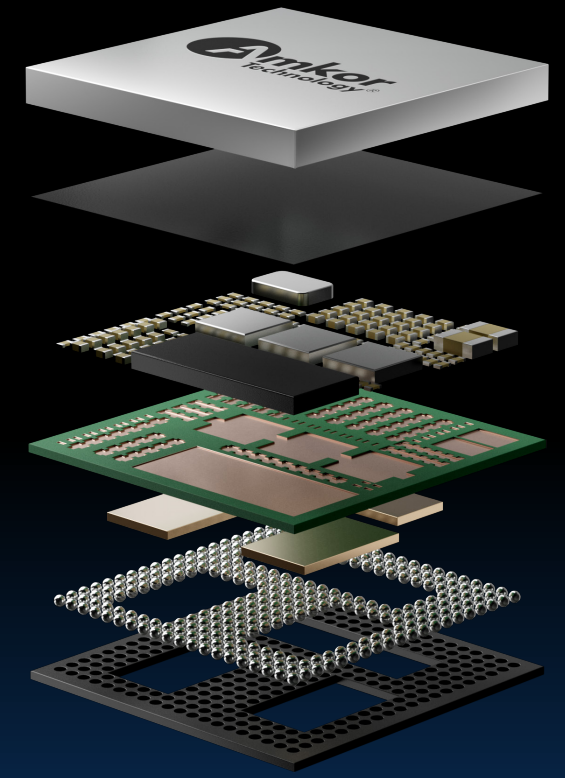
Monolithic SoC (System-on-Chip) : Components are integrated into a single silicon die
GDDR: Graphics Double Data Rate Memory
HBM : High Bandwidth Memory

PCB: Printed Circuit Board
OE : Optical Engine

Execution at Scale, Serving as Critical Bridge Between Advanced Silicon & Customers



Advanced Silicon

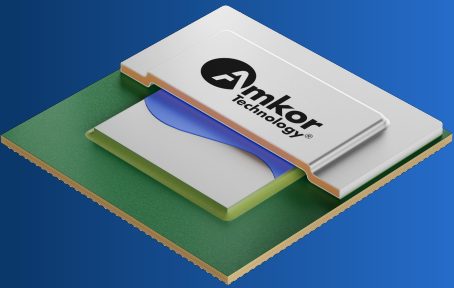


Customer Applications and Device Performance

A Scalable Advanced Packaging Platform Roadmap

Monolithic SoC

Optimized single-die performance



Flip Chip

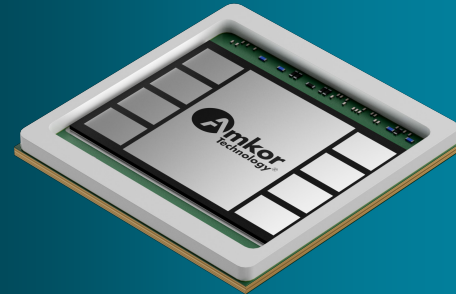
Direct die-to-substrate connections

Versatile, high-volume packaging

Cost-effective, mature design-rules, stable process

Heterogeneous Integration

Modular system-level scaling

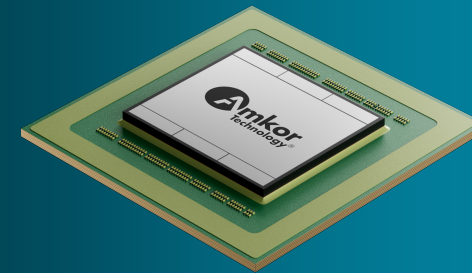


2.5D Platforms

Si interposer +TSV (through silicon via)

High bandwidth die-to-die connectivity

Logic + HBM integration

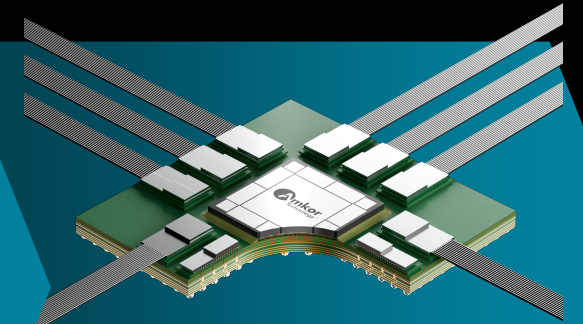


High-Density Fan-Out (HDFO)

Fine-line RDL interposer or Si bridge molded interposer for high I/O density

Attractive scaling economics

Modular design flexibility



Next-Gen Engagement

Early alignment as architectures evolve

Designed for manufacturability at scale

Advanced Packaging Pipeline

Package Type	# of Customers	# of Engagements
2.5D	11	18 Active Engagements 4 in production in 2026
HDFO RDL	5	10 Active Engagements 4 in production in 2026
HDFO Bridge	1	1 Active Engagement
CPO	3	3 Active Engagements

Powering Next-Generation Computing

“

NVIDIA's pace of innovation depends on a strong ecosystem of partners. Amkor has contributed Advanced packaging solutions that support the performance and reliability of our products.

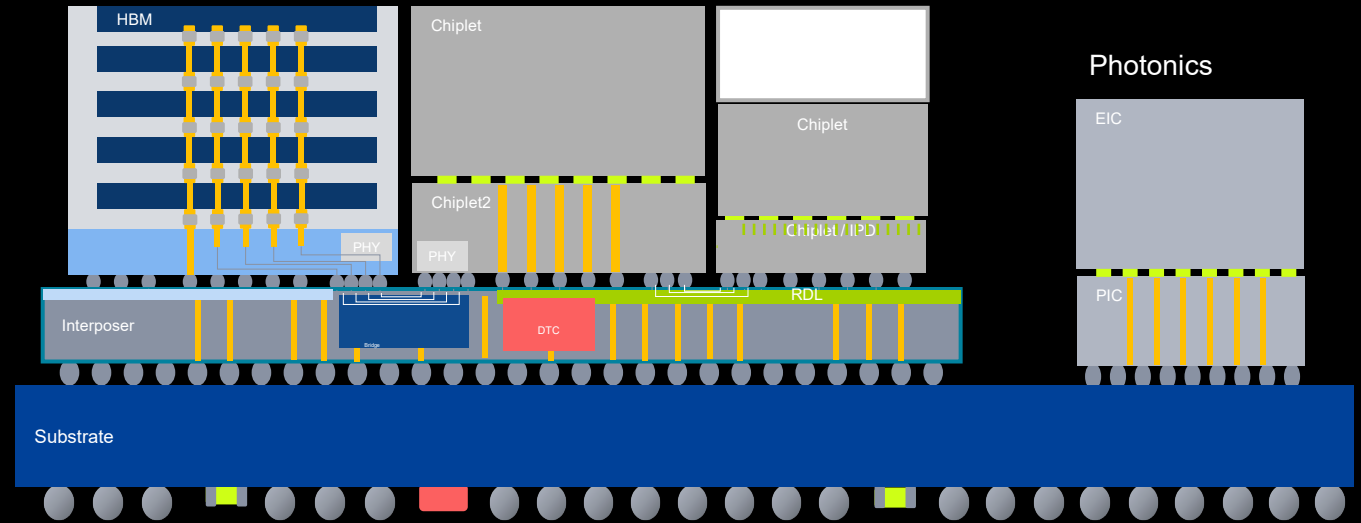
As AI demand continues to grow, collaborations like this enable the development and delivery of our new technologies, while ongoing investments in the U.S. support a more resilient supply chain. Our work with Amkor and the broader manufacturing ecosystem will advance the future of AI.”



NVIDIA

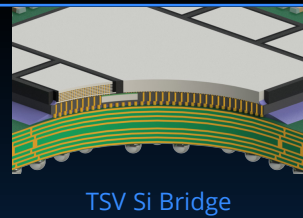
—Debora Shoquist | EVP, Operations

Package Solutions + Technology Toolboxes

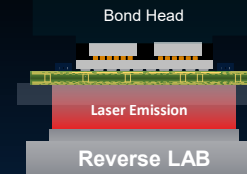


Technology Toolbox

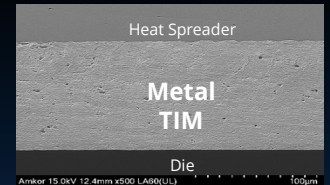
RDL & Bridge



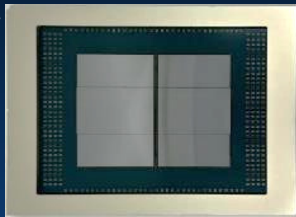
Advanced Chip Attach



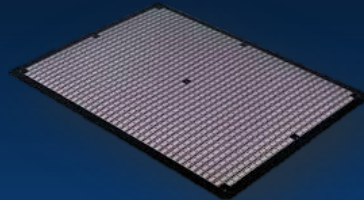
Thermal Enhancement



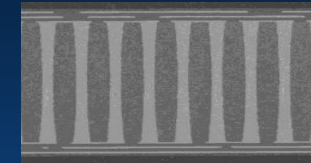
Large Body FCBGA



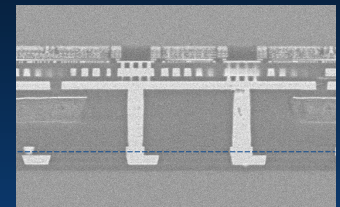
Large Panel Format



Glass Core Substrate



Hybrid Bonding

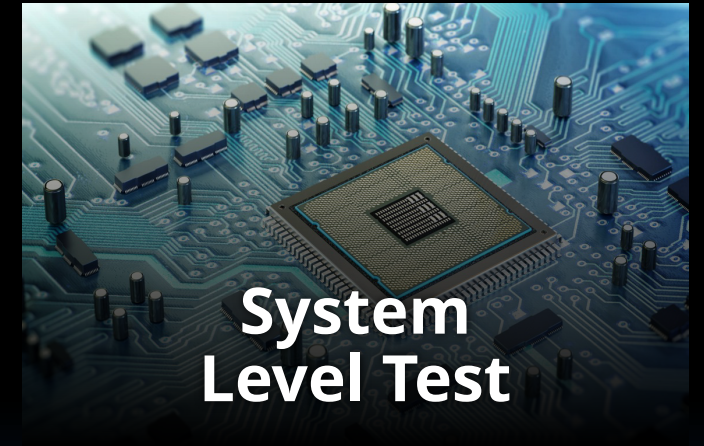
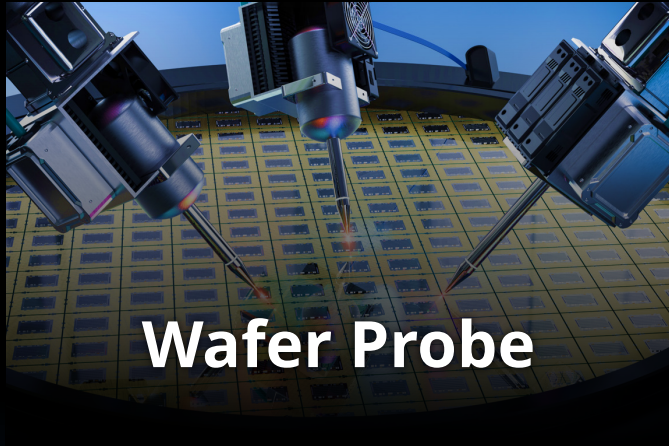


RDL: Redistribution layer
TSV: Through-silicon via
LAB: Laser assisted bonding

TIM: Thermal interface materials
IPD: Integrated passive device
DTC: Deep trench capacitor

EIC: Electronic integrated circuit
PIC: Photonic integrated circuit

Test Strategy



High value-add

Realtime yield and process monitoring

Turnkey support

Amkor's Evolving Turnkey Service Model

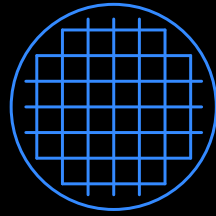
Reduce Cycle Time, Increase Value



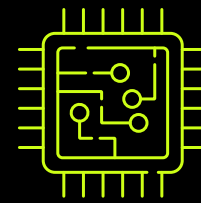
Design
Innovation



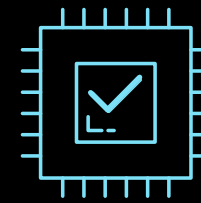
Materials
Management



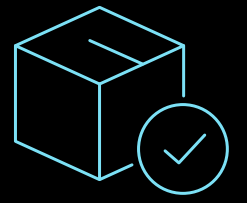
Wafer Bump,
Probe, Dicing



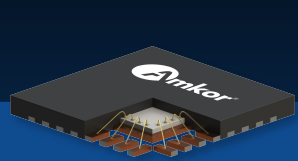
Package
Assembly



Final Test
Burn-in, SLT



Drop
Ship



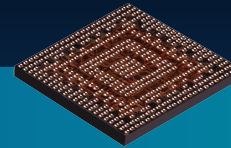
Leadframe, Power



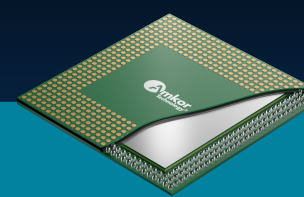
MEMS and Sensors



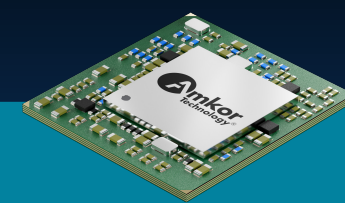
Memory



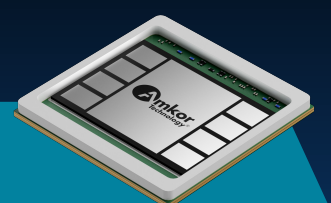
WLFO, WLCSP



Flip Chip, PoP MCM



SiP, Heterogeneous
Integration



2.5D, High-Density
Fan-Out

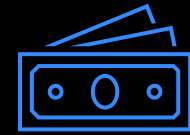
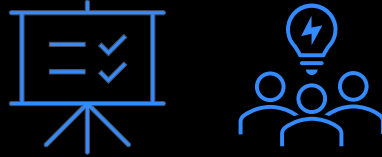
Mainstream/Wirebond

Advanced

Advanced Packaging Solutions Video



Technology Leadership Translates into Earnings Power



Technology Inputs

Early co-development with strategic customers

Scalable Advanced packaging platforms

Turnkey execution with packaging and test engineered together

Business Outcomes

Higher content per package

Longer program lifecycles

Participation in more complex, higher-value designs

Financial Impact

More favorable revenue mix

Margin accretion as programs scale

Enhanced earnings power over time

Disciplined execution drives better mix, scale, and margins

Elevating Technology Leadership Key Takeaways

1

Co-development is critical to solving complex power, performance, and form factor requirements

2

Technology roadmap is in lock-step with strategic customers

3

Accelerating Advanced packaging and test investments to reduce cycle time, improve yields, and deliver consistent execution

4

Higher-value product mix and margin accretion drives Earnings power

Break

Expanding Geographic Footprint



Doug Scott | CVP, Advanced & Mainstream Business Units

Intentional, Strategic Footprint

1 Intentionally built broad footprint

Geographic flexibility addressing need for regional manufacturing optionality

2 Amkor Arizona enables U.S. supply chain

We are a critical link enabling end-to-end U.S. semiconductor manufacturing

3 Leveraging global scale today, bridging to the U.S.

South Korea, Taiwan, Vietnam, and Portugal are purpose-built, providing volume, efficiency, and learning, while also bridging to U.S. production

4 Expanded intentional footprint driving financial outcomes

Footprint expansion unlocks flexibility, scale advantages, and incremental addressable market



Intentional & Strategic Global Footprint Providing Flexibility to Meet Customer Requirements

Factory network of **13M** square feet, spanning **9** countries*

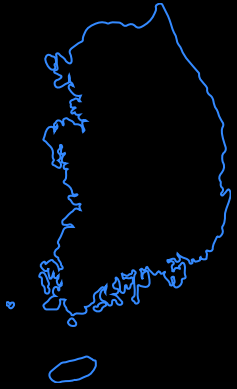


Capacity is demand-led

Footprint scaling is intentionally built

Designed to maximize utilization and returns

Purpose-Built Scale Today, Bridging to U.S. Production Tomorrow



South Korea

- Advanced packaging center of excellence
- R&D center of excellence
- Expanding footprint 20% in 2025/26



Vietnam

- Offers geodiversity
- Scaling SiP and memory
- Attractive cost structure



Taiwan

- Proximity to leading-edge foundry
- Advanced wafer level technology
- Flip chip, probe, and final test



Portugal

- Automotive supply resiliency
- Advanced wafer level and sensors technology
- Power module IDM partnerships

Arizona Advanced Packaging Facility Enables End-to-End U.S. Semiconductor Manufacturing

Key Highlights:

- Amkor is the only scaled Advanced packaging OSAT building in the U.S.
- High-value Advanced packaging and test focus
- Full turnkey (bump / probe / assembly / test) offering
- Highest level of automation
- Positioning for future growth: secured additional 67 acres in May 2026

2025

Today

2027

2028

Construction began in September

On schedule for 2027 build completion

Tool installation, line verification, and qualification

Production start



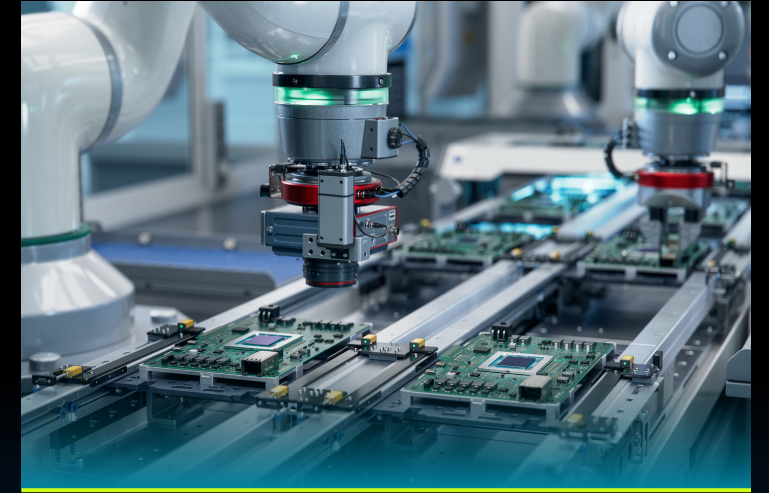
End-to-End Manufacturing Requires Ecosystem Alignment



Regional supply chains
require front-end and
back-end coordination



Advanced packaging
and test must scale in
lockstep with fab



Execution depends on
an intentionally built
footprint aligned to
the ecosystem

Strategic Alignment with the World's Leading Foundry

“ TSMC and Amkor have been long-standing, trusted partners in Asia, and our collaboration in Arizona extends this partnership to the United States.

Together, we combine advanced front-end fabrication with Advanced packaging and test to support customers' needs for geographic flexibility across end-to-end semiconductor manufacturing.”



—Dr. Kevin Zhang | Senior Vice President, Business Development and Global Sales & Deputy Co-COO

Amkor's Manufacturing Footprint Video



Expanding Geographic Footprint Key Takeaways

1

Intentionally built broad footprint addressing need for regional manufacturing optionality

2

Amkor's Arizona facility is a critical link that enables end-to-end U.S. semiconductor manufacturing

3

Our Advanced packaging locations in Asia and Europe are purpose-built scale engines bridging to U.S. production

4

Footprint expansion unlocks flexibility, scale advantages, and incremental addressable market

Turning Strategy Into Earnings Power



Megan Faust | EVP, Chief Financial Officer

Turning Strategy into Stronger Earnings Power

Invest, ramp, and leverage to drive shareholder value

1 Multi-year value creation path

Phase 1: 2025–2028 strategic investment and ramp

Phase 2: 2028–2030 ramp and leverage; translating into more than 3x earnings power by 2030

2 Each strategic pillar has a direct link to earnings power

Strategic partnerships: deeper and earlier engagement > better visibility
> aligned capacity planning > improved utilization > higher profitability

Technology leadership: higher-value mix and margin accretion at scale

Expanding footprint: incremental serviceable addressable market

3 Disciplined capital allocation

Strong balance sheet and operational excellence underpins performance



Long-Term Financial Targets

	2025 Results ⁽¹⁾	2028 Targets	2030 Targets
Revenue	\$6.7B	\$9.0B +/- \$500M	~\$11B+
Gross Margin	14%	17.5% +/- 100bps	~22%+
EPS	\$1.50	\$2.50 +/- \$0.25	~\$5.00+

KEY ASSUMPTIONS

Mix shift towards higher-value packaging drives margin and earnings expansion

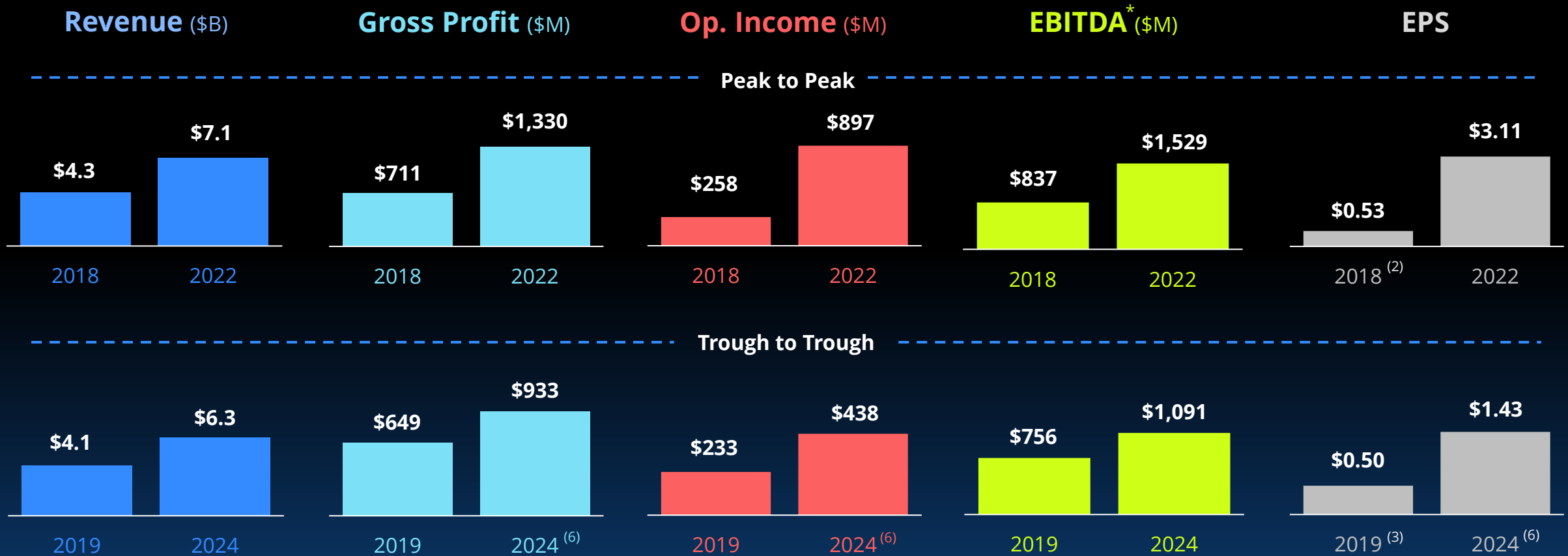
Initial ramp up costs in 2027 and 2028 with AZ buildout

Revenue growth accelerates in 2029–2030 as AZ facility scales

20% planning effective tax rate

See corresponding endnotes on slide 71.

Improved Operational & Financial Rigor are Driving Higher Highs & Higher Lows



Improved performance through cycle

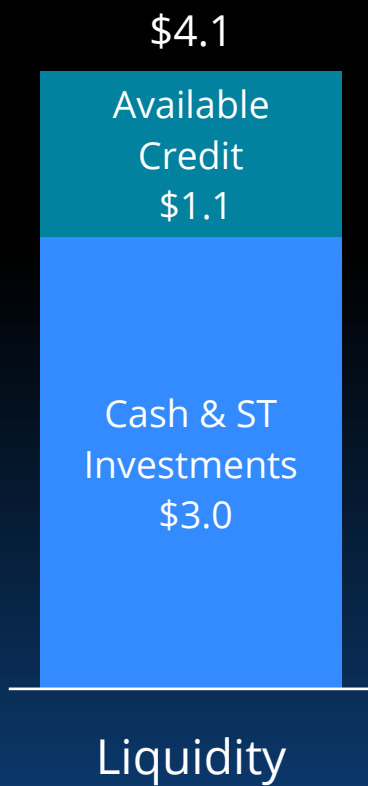
*See discussion of Non-GAAP measures on slide 70 and the reconciliation to the most directly comparable GAAP measure on slide 69.

See corresponding endnotes on slide 71.

Financial Flexibility to Support Strategic Growth Investments

(as of 3/31/2026 and proforma for \$1.2B Convertible Senior Notes issued 5/5/2026^{**}; \$ in billions)

Financial Flexibility



\$1.1B of availability on credit facilities and a net cash position

Issued \$1.2B of Convertible Senior Notes

~\$500M of cash needed for operations

Significant cash flow from ops



*See discussion of Non-GAAP measures on slide 70 and the reconciliation to the most directly comparable GAAP measure on slide 69.

**Excluding transaction related fees and expenses.

Balanced & Disciplined Capital Allocation Strategy



Invest in Organic Growth

Invest in manufacturing scale and in diversifying global footprint

Invest in R&D to enhance technology in partnership with lead customers



Strategic Investments

Support regional semiconductor supply chains

Tuck-in M&A for strategic business growth



Maintain Balance Sheet Strength & Flexibility

Long-term debt to EBITDA* target of 1.5x or below

Maintain strong liquidity for maximum flexibility



Shareholder Returns

Return 40-50% of Free cash flow* over time¹

Growth in regular quarterly dividend²

\$300M share repurchase authorization

Arizona Overview

KEY METRICS



\$7B

Total investment
across 2 phases



750K sq ft

of cleanroom
space



Multi-year
contracts
with **top
customers**

Phase 1

Included in financial targets

Construction underway

Facility anchored by key
customers

Phase 2

Not yet included in financial
targets

Customer commitments will
drive timing

Site preparation underway

Secured additional 67 acres in May 2026

PHASE 1 (AT FULL SCALE)

Revenue Contribution

~\$1B

Gross Margin

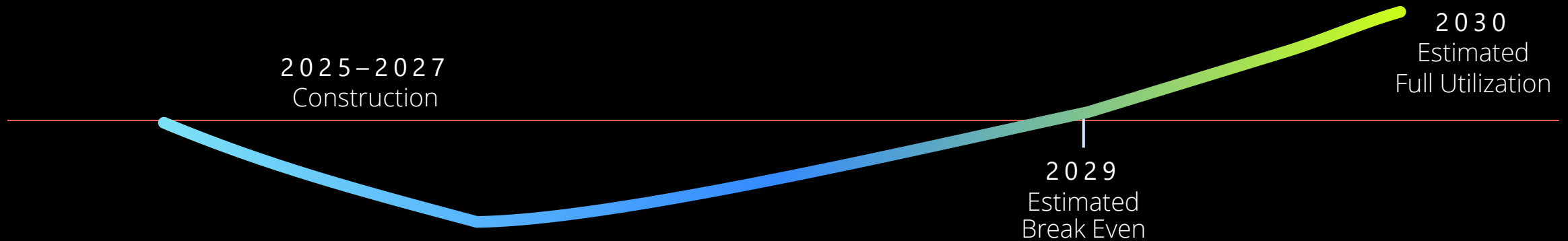
>30%

FUNDING SOURCES

- ✓ **\$3.0B cash**, \$1.1B credit facilities = \$4.1B liquidity**
- ✓ **Government incentives**
 - ~\$2B Investment tax credits (ITCs)
 - ~\$400M CHIPS
 - Land grant and \$35M other incentives
- ✓ **Partner co-investments**
- ✓ **Operating cash flow**
- ✓ **Capital markets**

**As of 3/31/2026 and proforma for \$1.2B Convertible Senior Notes issued on 5/5/2026, excluding transaction related fees and expenses.

Financial Framework: Arizona Advanced Packaging



INVEST

2025-2027

Construction

Capacity online

Qualification

Utilization building



RAMP

2028-2029

Utilization

Mix

Productivity compound



LEVERAGE

2030 & BEYOND

Sustained utilization and absorption

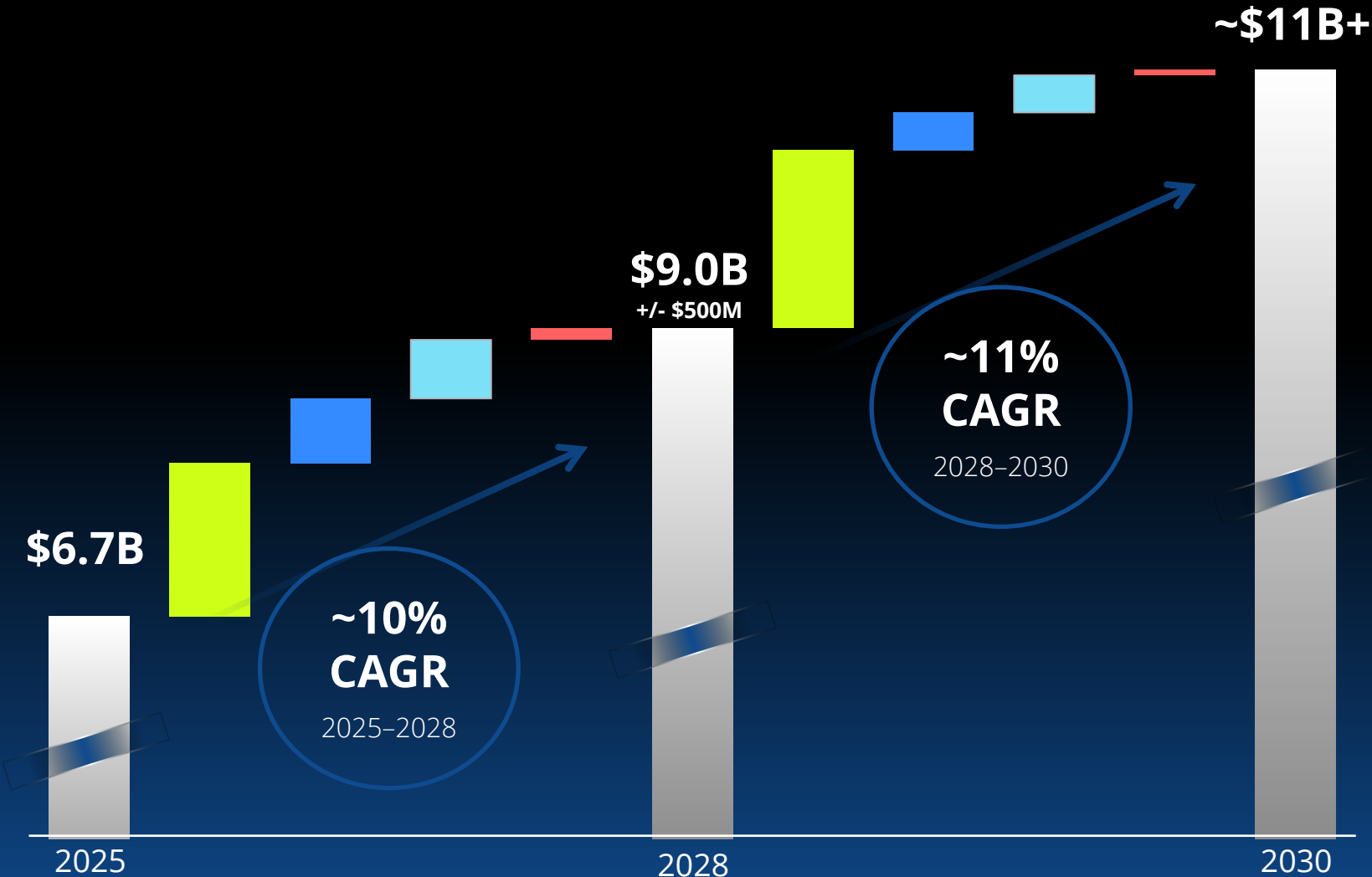
Mix shift toward higher-value advanced packaging

Productivity gains from platform reuse and automation

Full model leverage = utilization + mix + productivity

Revenue Growth

Arizona Facility Accelerates Growth in 2029–2030



KEY DRIVERS

Computing

- AI training and inference
- Data routing and networking
- XPU and ASIC solutions

Automotive & Industrial

- ADAS content increase
- Autonomous and software defined functionality

Communications

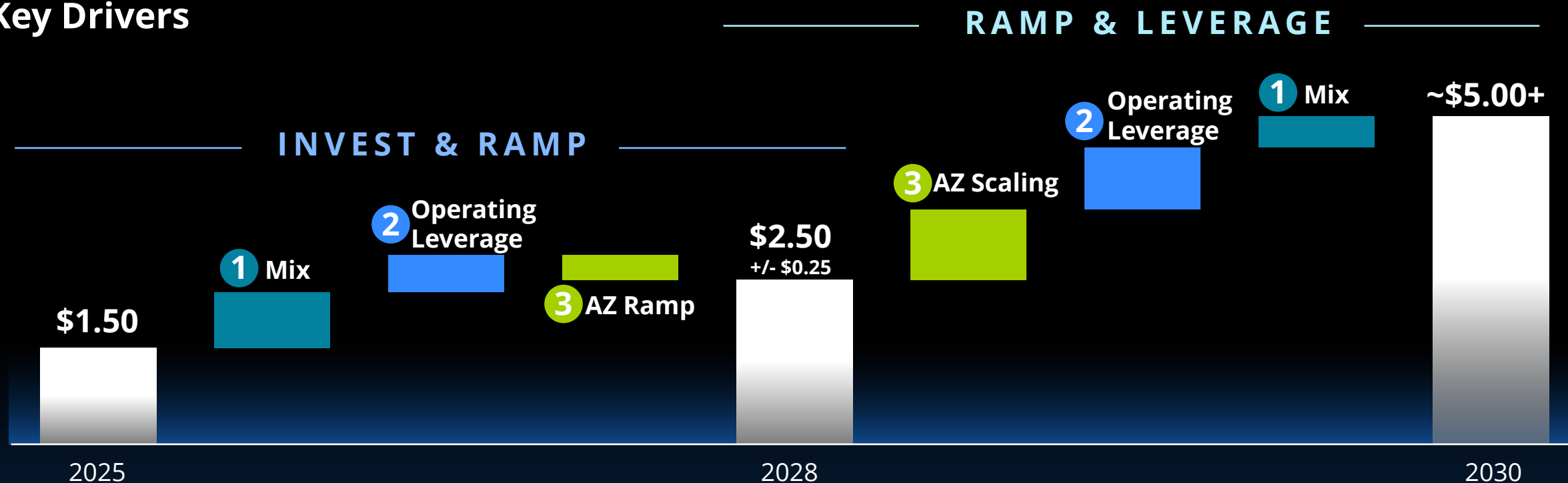
- On-device AI
- 5G and RF functionality

Consumer

- Wearables
- Connected everything
- Edge AI devices

Over 3X Earnings Power

Key Drivers



1 Mix

2 Operating Leverage

3 AZ Ramp & Scaling

2025-2028

Increasing contribution from higher-value Advanced packaging

Capacity deployment

Temporary ramp up costs until factory is at scale

2028-2030

Sustained mix shift

Automation compounds leverage from utilization and efficiencies

Arizona facility scales and becomes accretive

Turning Strategy into Earnings Power Key Takeaways

1

Amkor is on a multi-year value creation path; strategic investment phase as capacity comes online and scales

2

Strong revenue growth and increasing utilization, translating into more than 3x earnings power through operating leverage and mix

3

Global supply chain increases supply security and partnerships reduce risk, expand margins, and improve capital efficiency

Q&A

Closing Remarks

Invest with Us



Kevin Engel | President & Chief Executive Officer

Invest with Us

1 Structural shift

Structural changes are reshaping the industry, and Advanced packaging is on the critical path

2 Amkor's growth engine

Advanced packaging is Amkor's growth engine, and we are scaling our partnerships, technology, and footprint to deliver at scale

3 Multi-year value creation

Amkor is on a multi-year value creation path, investing today to drive a materially stronger earnings model over time

CLEAR PATH TO:

~\$11B+
Revenue

~22%+
Gross Margin

~\$5.00+
EPS



Thank You

Appendix

Financial Reconciliation Tables

(\$ in millions)	2018 ⁽²⁾	2019 ^{(3), (4)}	2020 ⁽⁵⁾	2021	2022	2023	2024 ⁽⁶⁾	2025 ⁽¹⁾	LTM Q126**
Net Income	\$130	\$123	\$340	\$646	\$767	\$362	\$356	\$376	\$438
Plus: Interest Expense	79	72	64	52	59	59	65	75	76
Plus: Income Tax Expense	56	37	46	69	90	82	75	69	77
Plus: Depreciation & Amortization	572	524	510	564	613	632	595	642	659
EBITDA*	\$837	\$756	\$960	\$1,331	\$1,529	\$1,135	\$1,091	\$1,162	\$1,250
Total Debt	\$1,332	\$1,450	\$1,154	\$1,138	\$1,232	\$1,203	\$1,159	\$1,445	\$2,564
Debt to Net Income	10.3	11.8	3.4	1.8	1.6	3.3	3.3	3.8	5.9
Debt to EBITDA*	1.6	1.9	1.2	0.9	0.8	1.1	1.1	1.2	2.1

See corresponding endnotes on slide 71.

*See discussion of Non-GAAP measures on slide 70.

**As of 3/31/2026 and proforma for \$1.2B Convertible Senior Notes issued on 5/5/2026, excluding transaction related fees and expenses.

Non-GAAP Measures

Generally, a non-GAAP financial measure is a numerical measure of a company's performance, financial position or cash flows that either excludes or includes amounts that are not normally excluded or included in the most directly comparable measure calculated and presented in accordance with U.S. GAAP.

In this presentation we refer to EBITDA and Debt to EBITDA (Leverage), which are not defined by U.S. GAAP. We define EBITDA as net income before interest expense, income tax expense and depreciation and amortization. Debt to EBITDA is calculated by dividing Total Debt by EBITDA for the period. We believe EBITDA and Debt to EBITDA to be relevant and useful information to our investors because they provide additional information in assessing our financial operating results. Our management uses EBITDA and Debt to EBITDA in evaluating our operating performance, and our ability to service debt, fund capital expenditures and pay dividends. However, EBITDA and Debt to EBITDA have certain limitations in that they do not reflect the impact of certain expenses on our consolidated statements of income, including interest expense, which is a necessary element of our costs because we have borrowed money in order to finance our operations, income tax expense, which is a necessary element of our costs because taxes are imposed by law, and depreciation and amortization, which is a necessary element of our costs because we use capital assets to generate income. EBITDA and Debt to EBITDA should be considered in addition to, and not as a substitute for, or superior to, operating income, net income, net income margin, debt to net income or other measures of financial performance prepared in accordance with U.S. GAAP. Furthermore, our definition of EBITDA may not be comparable to similarly titled measures reported by other companies. Please see Slide 69 for the reconciliation of these non-GAAP measures to the most directly comparable U.S. GAAP measures.

In this presentation we refer to free cash flow, which is not defined by U.S. GAAP. We define free cash flow as net cash provided by operating activities less payments for property, plant and equipment, plus proceeds from the sale of, insurance recovery for and grants for property, plant and equipment, if applicable. We believe free cash flow to be relevant and useful information to our investors because it provides them with additional information in assessing our liquidity, capital resources and financial operating results. Our management uses free cash flow in evaluating our liquidity, our ability to service debt, our ability to fund capital expenditures and our ability to pay dividends and the amount of dividends to be paid. However, free cash flow has certain limitations, including that it does not represent the residual cash flow available for discretionary expenditures since other, non-discretionary expenditures, such as mandatory debt service, are not deducted from the measure. The amount of mandatory versus discretionary expenditures can vary significantly between periods. This measure should be considered in addition to, and not as a substitute for, or superior to, other measures of liquidity or financial performance prepared in accordance with U.S. GAAP, such as net cash provided by operating activities. Furthermore, our definition of free cash flow may not be comparable to similarly titled measures reported by other companies.

Endnotes

1. For the year ended December 31, 2025, our results include a \$32 million net benefit to operating income and EBITDA due to a contingency payment related to our acquisition of Nanium in May 2017. Net income and earnings per diluted share also include a \$16 million and \$0.07 benefit, respectively.
2. 2018 net income includes a \$17 million discrete income tax charge, or \$0.07 per diluted share, driven by finalizing the accounting for U.S. tax reform.
3. 2019 net income includes an \$8 million charge, or \$0.03 per share, related to the early redemption of \$525 million of senior notes due 2022 and a net \$11 million discrete income tax charge, or \$0.05 per diluted share, related to changes in the valuation of certain deferred tax assets.
4. In Q1 2020, we repaid \$120 million of our term loan due December 2023 with proceeds from a term loan entered into in December 2019, thus increasing our outstanding debt at Q4 2019 period end.
5. 2020 net income includes a \$20 million discrete income tax benefit, or \$0.08 per diluted share, primarily related to changes in the valuation of certain deferred tax assets.
6. We periodically assess the estimated useful lives of our property, plant and equipment. Based on our assessment of test equipment and its increased interchangeability enabling broader and longer use, we extended the estimated useful lives of test equipment from five years to seven years as of January 1, 2024. As a result, depreciation expense was reduced by approximately \$59 million for the year ended December 31, 2024. This benefited net income by approximately \$49 million and diluted earnings per share by \$0.20. In addition, the reduction in depreciation expense benefited our gross margin by approximately 80 basis points for the year ended December 31, 2024.